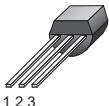


HAOPIN MICROELECTRONICS CO.,LTD.

Description

Passivated, sensitive gate triacs in a plastic envelope, intended for use in general purpose bidirectional switching and phase control applications, where high sensitivity is required in all four quadrants.

Symbol		Simplified outline
T2	T1	 TO-92
Pin	Description	
1	Main terminal 1 (T1)	
2	gate (G)	
3	Main terminal 2 (T2)	

Applications:

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

Features

- ◆ Blocking voltage to 600 V
- ◆ On-state RMS current to 1 A

SYMBOL	PARAMETER	Value	Unit
V_{DRM}	Repetitive peak off-state voltages	600	V
$I_T \text{ (RMS)}$	RMS on-state current	1	A
I_{TSM}	Non-repetitive peak on-state current	16	A

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
R_{thj-mb}	Thermal resistance Junction to mounting base	Full cycle	-	-	60	K/W
		Half cycle	-	-	80	K/W
R_{thj-a}	Thermal resistance Junction to ambient	Pcb mounted; lead length=4mm	-	150	-	K/W



BT131-600

Sensitive Gate Triacs

HAOPIN MICROELECTRONICS CO.,LTD.

Limiting values in accordance with the Maximum system(IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V_{DRM}	Repetitive peak off-state Voltages		-	600	V
$I_{T(RMS)}$	RMS on-state current	Full sine wave; $T_{lead} \leq 51^\circ C$	-	1	A
	Non-repetitive peak On-state current	full sine wave; $T_j = 25^\circ C$ prior to surge	$t=20ms$ $t=16.7ms$	16 17.6	A
I^2t	I^2t for fusing	$T=10ms$	-	1.28	A^2s
DI_T/dt	Repetitive rate of rise of on-state current after triggering	$I_{TM}=1.5A$; $IG=0.2A$; $D_{IG}/dt=0.2A/\mu s$	$T2+G+$	-	$50 A/\mu s$
			$T2+G-$	-	$50 A/\mu s$
			$T2-G-$	-	$50 A/\mu s$
			$T2-G+$	-	$10 A/\mu s$
I_{GM}	Peak gate current		-	2	A
V_{GM}	Peak gate voltage		-	5	V
P_{GM}	Peak gate power		-	5	W
$P_{G(AV)}$	Average gate power	Over any 20 ms period	-	0.5	W
T_{stg}	Storage temperature		-40	150	$^\circ C$
T_j	Operating junction Temperature		-	125	$^\circ C$

$T_j=25^\circ C$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	
Static characteristics							
I_{GT}	Gate trigger current	$V_D=12V$; $I_T=0.1A$	$T2+G+$ $T2+G-$ $T2-G-$ $T2-G+$	- - - -	0.4 1.3 1.4 3.8	3 3 3 7	mA mA mA mA
I_L	Latching current	$V_D=12V$; $I_{GT}=0.1A$	$T2+G+$ $T2+G-$ $T2-G-$ $T2-G+$	- - - -	1.2 4.0 1.0 2.5	5 8 5 8	mA mA mA mA
I_H		$V_D=12V$; $I_{GT}=0.1A$		-	1.3	5	mA
V_T	On-state voltage	$I_T=2.0A$		-	1.2	1.5	V
V_{GT}	Gate trigger voltage	$V_D=12V$; $I_T=0.1A$ $V_D=400V$; $I_T=0.1A$; $T_j=125^\circ C$		- 0.2	0.7 0.3	1.5 -	V V
I_D	Off-state leakage current	$V_D=V_{DRM(max)}$; $T_j=125^\circ C$		-	0.1	0.5	mA

Dynamic Characteristics

D_{VD}/dt	Critical rate of rise of Off-state voltage	$V_{DM}=67\% V_{DRM(max)}$; $T_j=125^\circ C$; Exponential wave form; $R_{GK}=1k\Omega$	5	15	-	$V/\mu s$
t_{gt}	Gate controlled turn-on time	$I_{TM}=1.5A$; $V_D=V_{DRM(max)}$; $I_G=0.1A$; $D_{IG}/dt=5A/\mu s$	-	2	-	μs

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Description

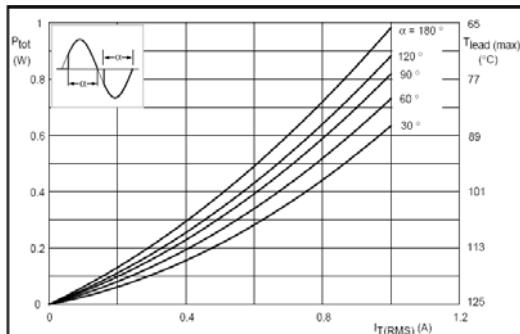


Fig.1. Maximum on-state dissipation, P_{otp} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

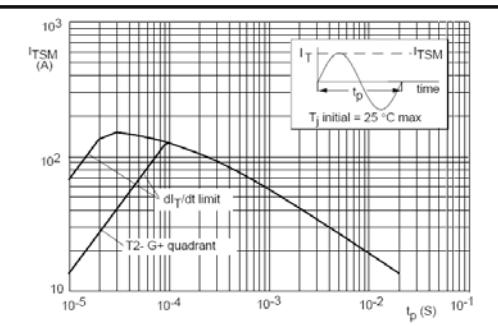


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20\text{ms}$.

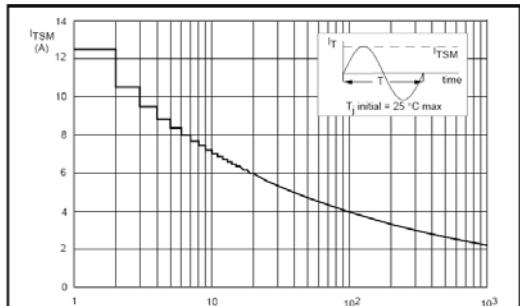


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, $f = 50\text{ Hz}$.

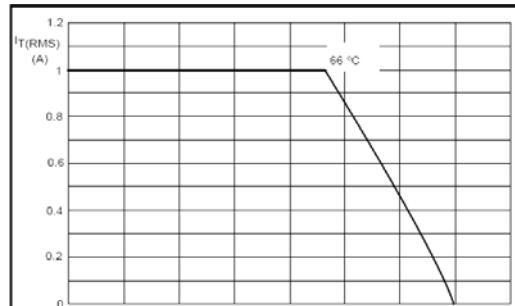


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus lead temperature T_{lead} .

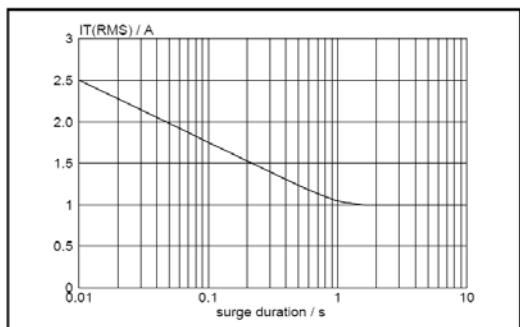


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50\text{ Hz}$; $T_{lead} \leq 66^\circ\text{C}$.

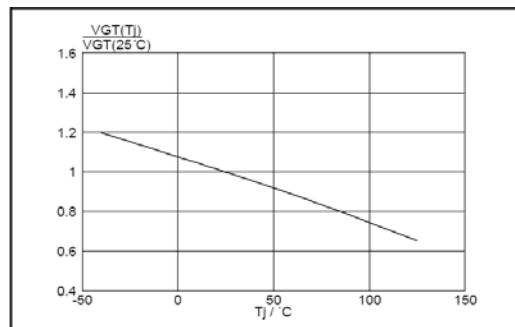


Fig.6. Normalised gate trigger voltage $V_{GT}(T)/V_{GT}(25^\circ\text{C})$, versus junction temperature T_j .

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Description

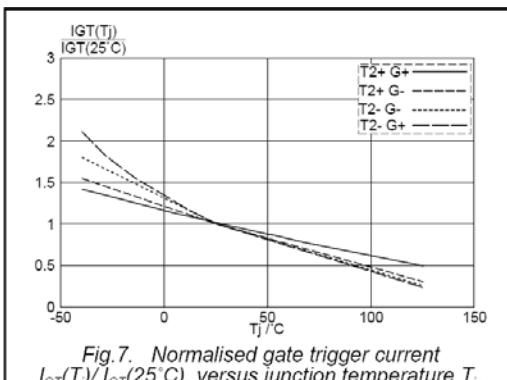


Fig. 7. Normalised gate trigger current
 $I_{GT}(T_j)/I_{GT}(25^\circ C)$, versus junction temperature T_j .

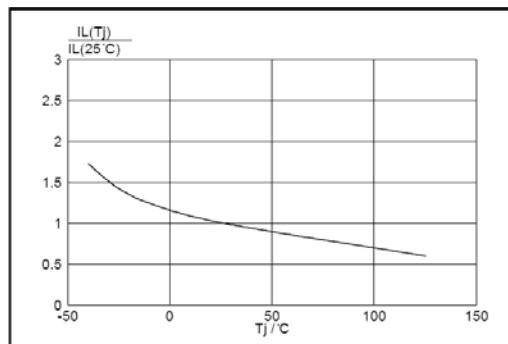


Fig. 8. Normalised latching current $I_L(T_j)/I_L(25^\circ C)$, versus junction temperature T_j .

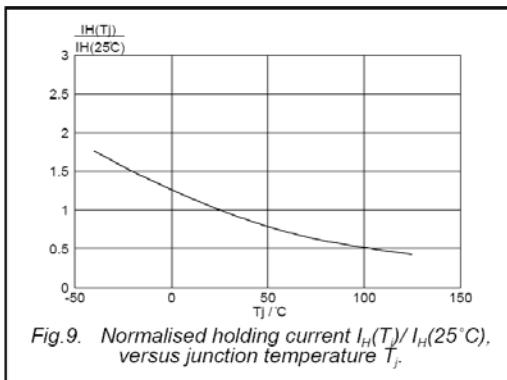


Fig. 9. Normalised holding current $I_H(T_j)/I_H(25^\circ C)$, versus junction temperature T_j .

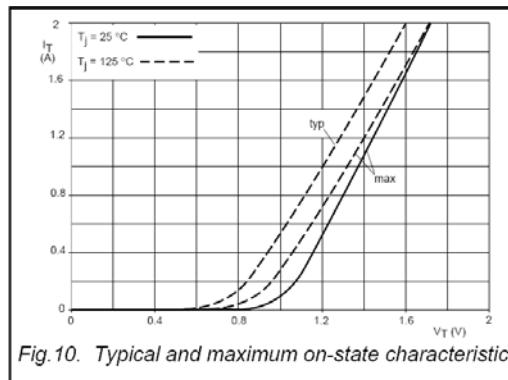


Fig. 10. Typical and maximum on-state characteristic.

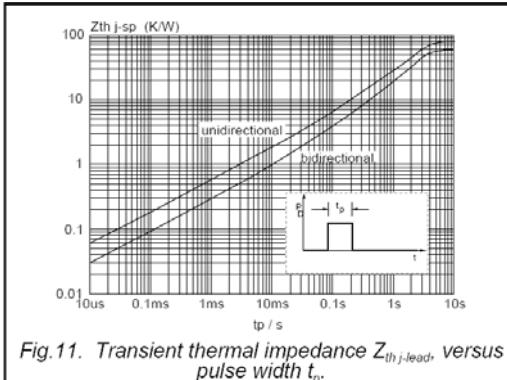


Fig. 11. Transient thermal impedance $Z_{th(j-lead)}$, versus pulse width t_p .

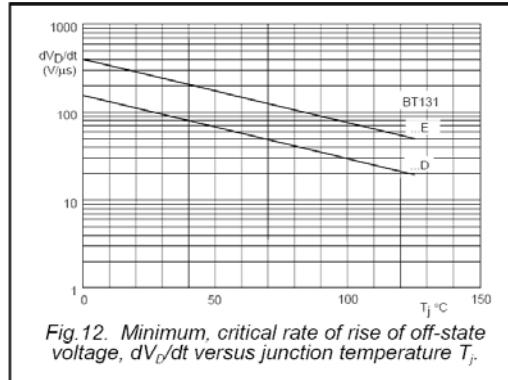


Fig. 12. Minimum, critical rate of rise of off-state voltage, dV/dt versus junction temperature T_j .

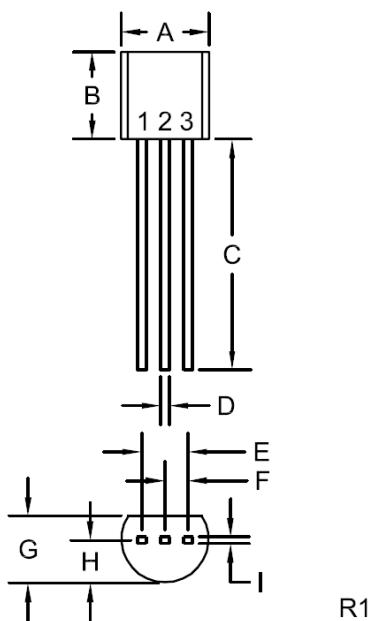
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MECHANICAL DATA

Dimensions in mm

Net Mass: 0.2 g

TO-92



SYMBOL	DIMENSIONS			
	INCHES	MILLIMETERS	MIN	MAX
A (DIA)	0.175	0.205	4.45	5.21
B	0.170	0.210	4.32	5.33
C	0.500	-	12.70	-
D	0.016	0.022	0.41	0.56
E	0.100	-	2.54	-
F	0.050	-	1.27	-
G	0.125	0.165	3.18	4.19
H	0.080	0.105	2.03	2.67
I	0.015	-	0.38	-

TO-92 (REV: R1)